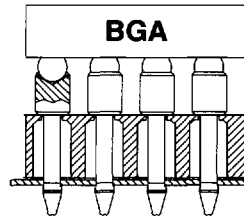
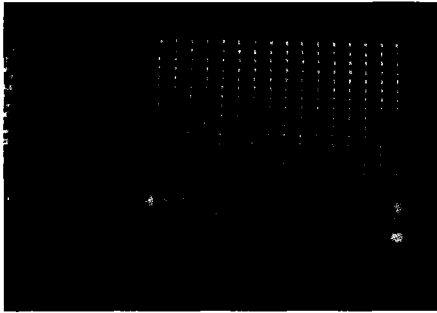
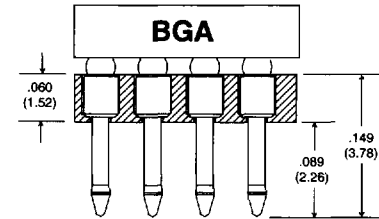


BGA Adapter with Removable Insulator



Before Soldering BGA to Adapter



After Soldering BGA & Inspection With Insulator Inverted and Reassembled

Features:

- Soldering BGA to adapter subjects BGA to less thermal stress than soldering BGA to a mother board due to the adapters lower mass.
- Countersink in head of pin allows easy positioning of BGA onto adapter.
- Custom adapters available for heat sink attachment.

Terminals:

Brass - Copper Alloy 360, ASTM-B-16

Plating:

Gold over Nickel or Tin-Lead over Nickel

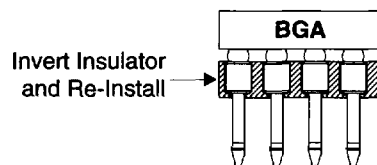
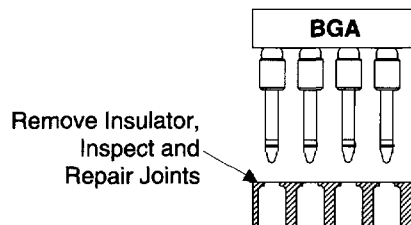
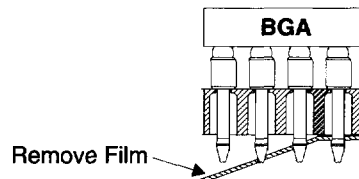
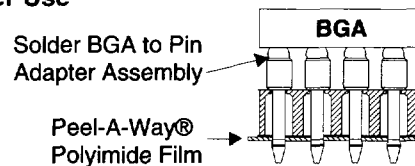
Body Material:

FR-4 - U.L. Rated 94V-O, Index 140°C (284°F)

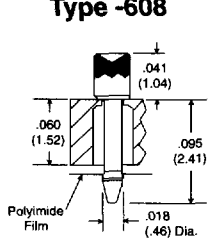
Glass Filled Thermoplastic Polyester (P.B.T.), U.L. Rated 94V-O, -60°C to 140°C (-76°F to 284°F)

Polyimide Film - -269°C to 400°C (-452°F to 752°F)

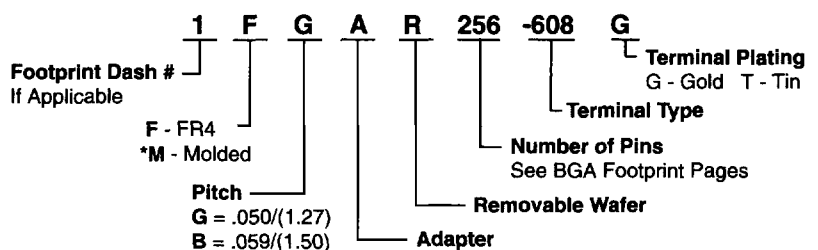
Adapter Use



Terminal Type -608



How To Order



* Preliminary - Consult Factory for Availability